# **DSA4005**

#### Silicon PNP epitaxial planar type

For general amplification Complementary to DSC4005 DSA2005 in NS through hole type package

#### Features

- $\bullet$  High forward current transfer ratio  $h_{\text{FE}}$  with excellent linearity
- Low collector-emitter saturation voltage  $V_{CE(sat)}$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

#### Packaging

DSA4005×0A Radial type : 5000 pcs / carton

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	-60	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	-50	V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	-6	V
Collector current	I <sub>C</sub>	-200	mA
Peak collector current	I <sub>CP</sub>	-300	mA
Collector power dissipation	P <sub>C</sub>	300	mW
Junction temperature	Tj	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

#### Package

- Code
- NS-B2-B-B

Package dimension clicks here.  $\rightarrow$ 

#### • Pin Name

- 1. Emitter
- 2. Collector
- 3. Base

#### Marking Symbol: A3

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -100 \ \mu {\rm A}, \ I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = -60 \text{ V}, I_E = 0$			- 0.1	μΑ
Emitter-base cutoff current (Collector open)	I <sub>EBO</sub>	$V_{EB} = -6 \text{ V}, I_C = 0$			- 0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = -6 \text{ V}, I_C = -1 \text{ mA}$	150		390	
	h <sub>FE2</sub>	$V_{CE} = -6 \text{ V}, I_C = -0.1 \text{ mA}$	90			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$			- 0.3	V
Transition frequency	$f_{T}$	$V_{CE} = -6 \text{ V}, I_C = -10 \text{ mA}$		150		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -6 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		5.0		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

#### 2. \*1: Pulse measurement

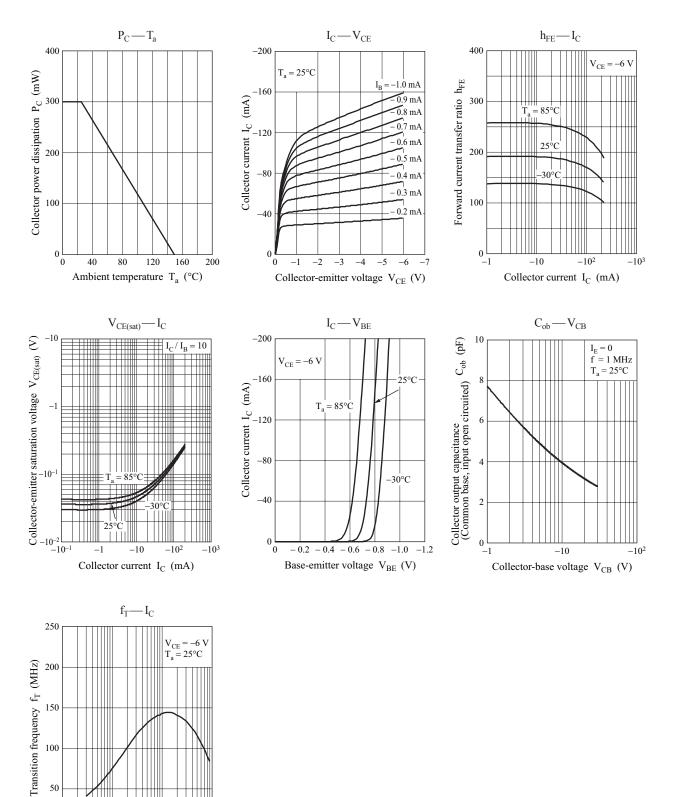
\*2: Rank classification

Code	R	S	0
Rank	R	S	No-rank
h <sub>FE1</sub>	150 to 270	200 to 390	150 to 390
Marking Symbol	A3R	A3S	A3

Product of no-rank is not classified and have no marking symbol for rank.

#### DSA4005

### **Panasonic**



 $-10^{2}$ 

-10

 $^{-1}$ 

Collector current  $I_C$  (mA)

0

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